



**12500 TI Boulevard, MS 8640, Dallas, Texas 75243**

**PCN# 20240202009.1**

**Qualification of RFAB as an additional Fab site option, Die Revision, and BOM Option  
for select devices**

**Change Notification / Sample Request**

**Date:** February 02, 2024

**To:** MOUSER PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments (TI). The details of this change are on the following pages, and are in alignment with our standard product change notification (PCN) [process](#).

TI requires acknowledgement of receipt of this notification within 30 days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance and approval of this change. If samples or additional data are required, requests must be received within 30 days of this notification, given that samples are not built ahead of the change.

The Proposed First Ship date in this PCN letter is the earliest possible date that customers could receive the changed material. It is our commitment that the changed device will not ship before that date. If samples are requested within the 30 day sample request window, customers will still have 30-days to complete their evaluation regardless of the proposed 1st ship date.

This particular PCN is related to TI's multiyear transition plan for our two remaining factories with 150-millimeter production (DFAB in Dallas, Texas, and SFAB in Sherman, Texas). DFAB will remain open, but will focus on 200-mm production, with a smaller set of technologies. SFAB will close no earlier than 2024 and no later than 2025. As referenced in the "reason for change" below, these changes are part of our multiyear plan to transition these products to newer, more efficient manufacturing processes and technologies, underscoring our commitment to product longevity and supply continuity.

For questions regarding this notice or to provide acknowledgement of this PCN, you may contact your local Field Sales Representative or the Change Management team. For sample requests or sample related questions, contact your local Field Sales Representative. As always, we thank you for your continued business.

Change Management Team  
SC Business Services

**20240202009.1**  
**Attachment: 1**

**Products Affected:**

The devices listed on this page are a subset of the complete list of affected devices. According to our records, you have recently purchased these devices. The corresponding customer part number is also listed, if available.

<b>DEVICE</b>	<b>CUSTOMER PART NUMBER</b>
TLC352IPWR	NULL
TLC372CPWR	NULL
TLV2352IPWR	NULL

Technical details of this Product Change follow on the next page(s).

<b>PCN Number:</b>	20240202009.1	<b>PCN Date:</b>	February 02, 2024
<b>Title:</b>	Qualification of RFAB as an additional Fab site option, Die Revision, and BOM Option for select devices		
<b>Customer Contact:</b>	Change Management Team	<b>Dept:</b>	Quality Services
<b>Proposed 1<sup>st</sup> Ship Date:</b>	May 2, 2024	<b>Sample requests accepted until:</b>	Mar 2, 2024*

**\*Sample requests received after March 2, 2024 will not be supported.**

**Change Type:**

<input type="checkbox"/>	Assembly Site	<input checked="" type="checkbox"/>	Design	<input type="checkbox"/>	Wafer Bump Material
<input type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Data Sheet	<input type="checkbox"/>	Wafer Bump Process
<input checked="" type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change	<input checked="" type="checkbox"/>	Wafer Fab Site
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site	<input checked="" type="checkbox"/>	Wafer Fab Material
<input checked="" type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process	<input checked="" type="checkbox"/>	Wafer Fab Process

**PCN Details**

**Description of Change:**

Texas Instruments is pleased to announce the qualification of its RFAB fabrication facility as an additional Wafer Fab option in addition to a BOM option for the devices listed below.

Current Fab Site			Additional Fab Site		
Current Fab Site	Process	Wafer Diameter	Additional Fab Site	Process	Wafer Diameter
DL-LIN	LINCMOS	150 mm	RFAB	LBC9	300 mm

The die was also changed as a result of the process change.

Additional BOM items are as follows:

	Current	Proposed
Die Thickness	10.5 mil	7.5 mil
Wire diam	0.96mil	0.80mil

Package marking change:

Package Marking (Sample)	Current	Proposed
	O TI/ YM TY2352	O TI YMS TY2352 (CAV)
	TI/ = TI LOGO YM = YEAR MONTH DATE CODE O = PIN 1 INDICATOR (DIMPLE)	TI = TI LETTER YM = YEAR MONTH DATE CODE S = ASSEMBLY SITE CODE O = PIN 1 INDICATOR (DIMPLE) CAV = CAVITY NUMBER

Qual details are provided in the Qual Data Section.

**Reason for Change:**

These changes are part of our multiyear plan to transition products from our 150-millimeter factories to newer, more efficient manufacturing processes and technologies, underscoring our commitment to product longevity and supply continuity.

**Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):**

None

**Impact on Environmental Ratings**

Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.

RoHS	REACH	Green Status	IEC 62474
<input checked="" type="checkbox"/> No Change			

#### Changes to product identification resulting from this PCN:

##### Fab Site Information:

Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City
DL-LIN	DLN	USA	Dallas
<b>RFAB</b>	<b>RFB</b>	<b>USA</b>	<b>Richardson</b>

##### Die Rev:

**Current**      **New**

Die Rev [2P]	<b>Die Rev [2P]</b>
E, C	<b>A</b>

Sample product shipping label (not actual product label):



##### Product Affected:

TL352IPWR	TL372CPWR	TLV2352IPWR
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For alternate parts with similar or improved performance, please visit the product page on [TI.com](http://TI.com)

### Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: TLC352IPWR	QBS Reference: LM2902BQPWRQ1	QBS Reference: TPS43000PW	QBS Reference: SN74LV8T245QPWRQ1	QBS Reference: TPS71550DCKRM3	QBS Reference: LM2901BQPWRQ1	QBS Reference: PSN2012025A12AACJR	QBS Reference: PSN2012025A12CACJR
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	3/231/0	-	1/77/0	-	1/77/0	-	-
UHAST	A3	Unbiased HAST	110C/85%RH	264 Hours	-	3/231/0	-	-	-	-	-	-
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	-	-	-	1/77/0	-	1/77/0	-	-
TC	A4	Temperature Cycle	-55C/125C	700 Cycles	-	-	-	-	-	-	-	-
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	-	3/231/0	3/231/0	1/77/0	-	1/77/1	-	-
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	3/231/0	-	-	-	-	-	-
HTSL	A6	High Temperature Storage Life	170C	420 Hours	-	-	3/231/0	-	-	-	-	-
HTSL	A6	High Temperature Storage Life	175C	500 Hours	-	-	-	1/45/0	-	1/77/0	-	-
HTOL	B1	Life Test	125C	1000 Hours	-	-	-	-	3/231	-	2/154/0	1/77/0
HTOL	B1	Life Test	150C	300 Hours	-	-	-	1/77/0	-	-	-	-
HTOL	B1	Life Test	150C	408 Hours	-	3/231/0	-	-	-	-	-	-
ESD	E2	ESD CDM	-	1000 Volts	1/3/0	-	-	-	-	-	-	-
ESD	E2	ESD HBM	-	2000 Volts	1/3/0	-	-	-	-	-	-	-
LU	E4	Latch-Up	Per JESD78	-	1/3/0	-	-	-	-	-	-	-
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/3/0	-	-	-	-	-	-	-

- QBS: Qual By Similarity
- Qual Device TLC352IPWR is qualified at MSL1 260C

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

TI Qualification ID: R-CHG-2310-049

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.

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